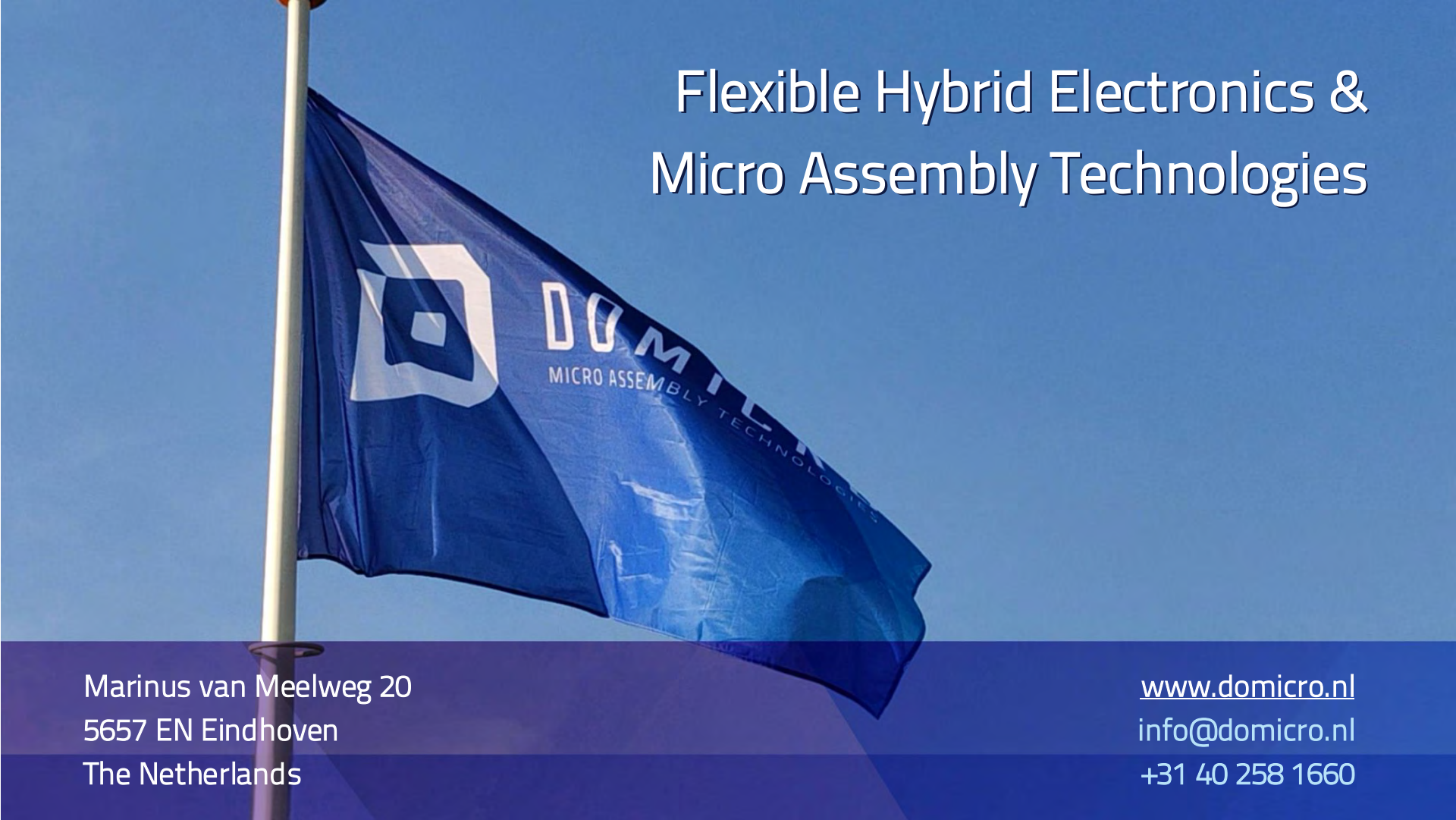


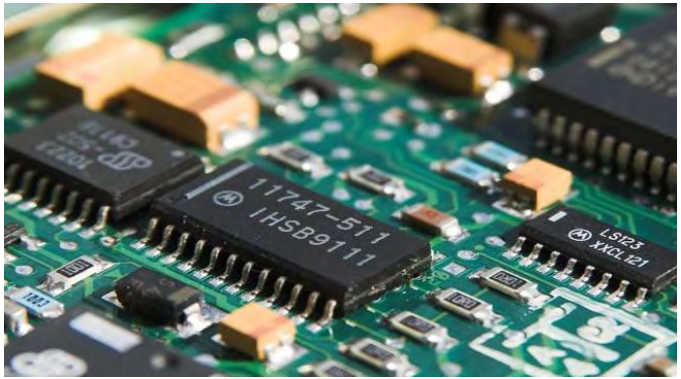
Flexible Hybrid Electronics & Micro Assembly Technologies

Marinus van Meelweg 20
5657 EN Eindhoven
The Netherlands

www.domicro.nl
info@domicro.nl
+31 40 258 1660

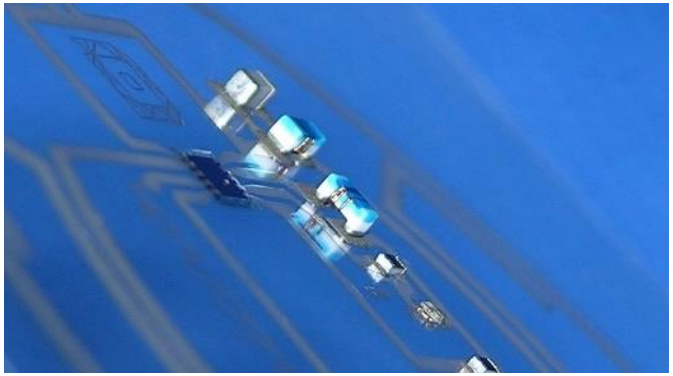
Conventional electronics

- Rigid PCBs
- Suitable for very complex applications
- Extended manufacturing capability



Flexible Hybrid Electronics

- More and new applications
- Suitable for integrated technology form-factor
- Additive technology



DOMICRO
MICRO ASSEMBLY TECHNOLOGIES

FLEXIBLE HYBRID ELECTRONICS

MICRO ASSEMBLY TECHNOLOGY

INKJET PRINTED ELECTRONICS

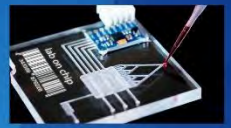
ADVANCED PACKAGING

DOMICRO COMPANY PROFILE

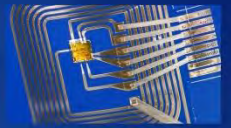
DoMicro BV is a technology company providing innovative manufacturing technology, application solutions and micro assembly technology for flexible hybrid electronics (FHE) and micro devices. More information: **www.domicro.nl**



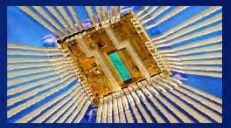
Automotive
Inmould



MedTech
Microfluidics



Wearables



Semicon
Micro Assembly



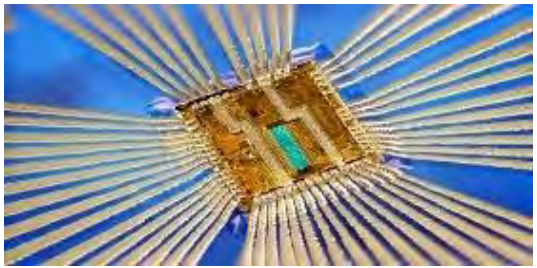
Solar



PCBA
Printing



Flexible Electronics
Printing



- Technology consultancy
- Contract research and development
- Development of prototypes
- Application development and electronic design

Developing proprietary technology

IP in manufacturing process to be marketed and licensed to key customers worldwide.

Long-term customer partnerships

Driving innovation via research & development into proof of concepts and proto realization.



GENERAL PRODUCT DEVELOPMENT METHODOLOGY



Finding the materials, processes and composition that could create functionality.
Learning about boundary conditions and limitations.
Report on research and eventually build a proof of concept (PoC)

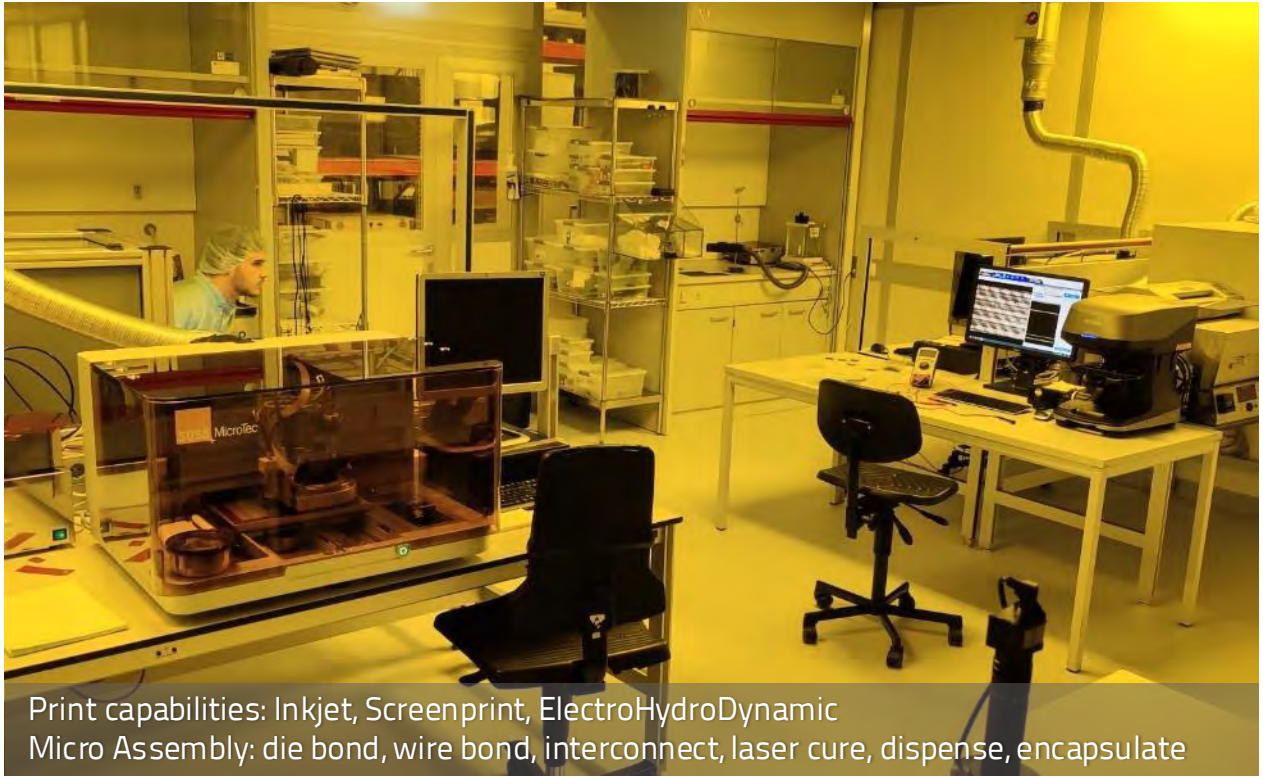
Combining the materials, processes into a configuration that could create functionality.
Building a prototype demonstrating basic functionality for the application.

Testing a small series (10 pcs) of prototypes into endurance, load and environmental circumstances of the application yielding information on stability, functional limitations and failure modes.
Finding areas for improvement and implement design iterations.

Running small series of products (100 pcs) to characterize processes and process windows.
Determine initial yield data, capability (Cpk) and variance analysis.
Qualify product to standards and legislation. Verify sales potential by exposure to the market.

Design production system architecture, equipment, tools, supply, sourcing.
Define tact time (OEE), material handling, quality control procedures and
Insights in cost structure (OPEX) and investment (CAPEX)

MICRO ASSEMBLY & PRINTED ELECTRONICS LAB



Print capabilities: Inkjet, Screenprint, ElectroHydroDynamic
Micro Assembly: die bond, wire bond, interconnect, laser cure, dispense, encapsulate



Inkjet printed wirebonding



Micro positioning and die bond



System integration electronics

Electrojet™ Turn-key additive manufacturing systems

Multi-layer PCB printing for electronics



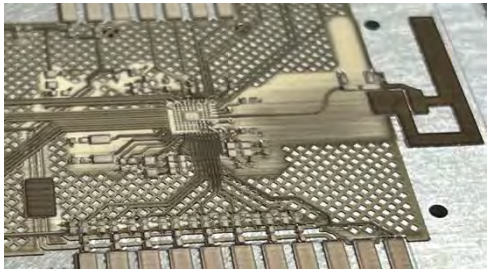


Product specifications	ElectroUV3D-1216 (Desktop)	ElectroUV3D-3200 (Production)
Feature size/spacing	100 µm / 200 µm	100 µm / 200 µm
Layer to layer accuracy	10 µm	10 µm
Throughput	n.a.	16m²/h (2 printheads)
Printing platform	30,5 cm x 40,6 cm (12" x 16")	90 cm x 60 cm (36" x 24")
Equipment dimensions	96,5 cm x 88,9 cm x 61 cm (38" W x 35" D x 24" H)	200 cm x 133,2 cm x 78,7 cm (78,6" W x 52,4" D x 31" H)
Weight	60 kg	155 kg

CHEMCUBED
Jettable Solutions.™

Multi-Material, Multi-Layer Capabilities

ElectroJet™ equipment and inks enable digital printing of advanced particle-free silver conductive inks and UV-curable dielectric insulating/building inks on low temperature. The platform features inline LED UV curing and inline heat sintering. Capabilities of the inkjet printed conductive inks match traditional etched PCB's, thus providing a more sustainable match with current applications.



Benefits

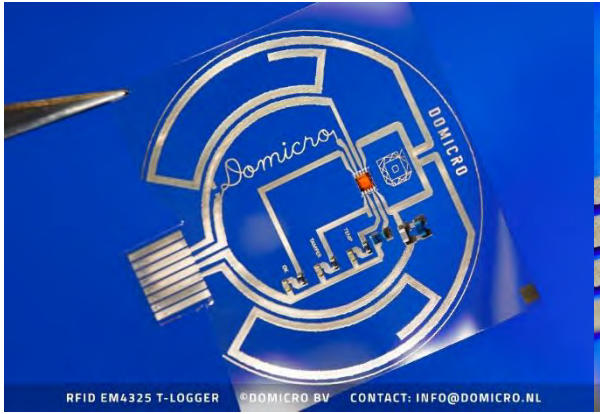
Fast prototyping Flexibility to design, prototype and produce compatible with the majority of digitally printed electronic applications, keeping your IP safe.

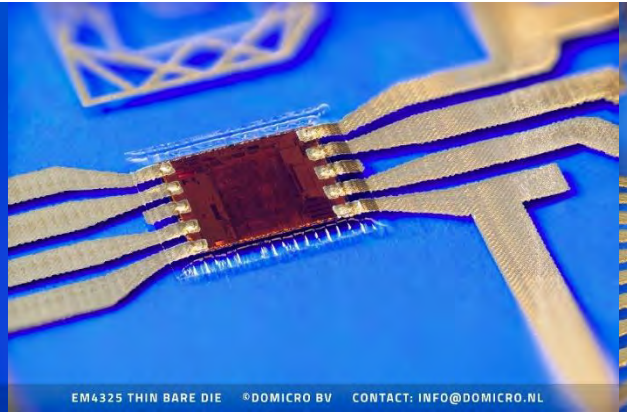
Performance Multi-layer capabilities & bulk silver conductive inks for unparalleled high performance.

Sustainable Digital additive manufacturing inkjet printing process replaces multiple conventional production steps by depositing only the required material, significantly reducing circuit dimensions.

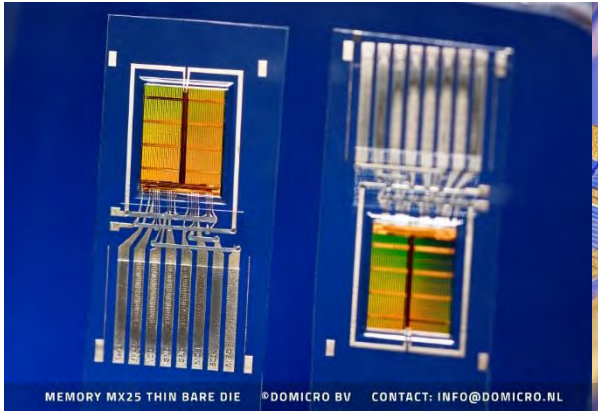


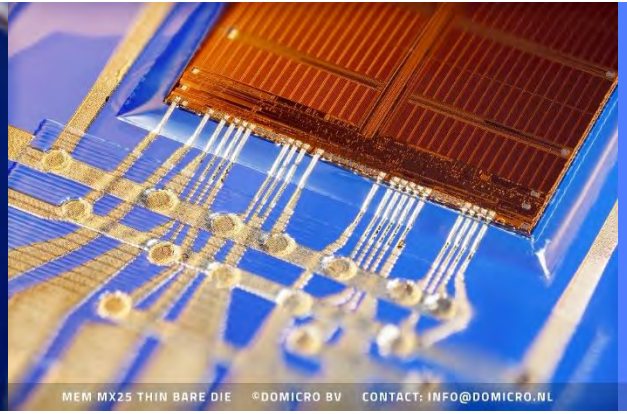
FHE TECHNOLOGY DEMONSTRATORS





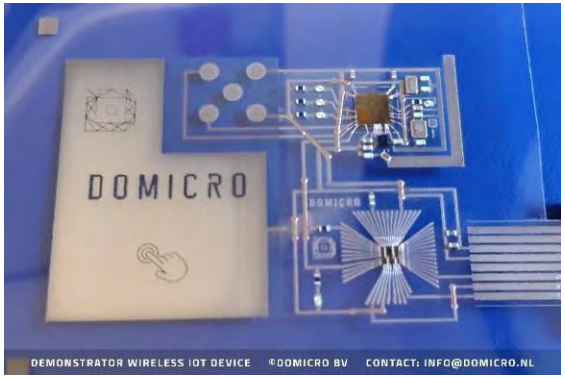


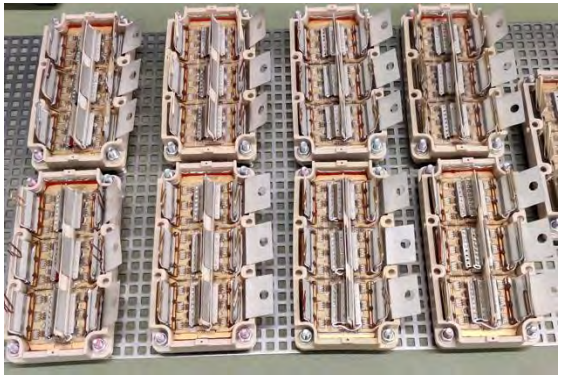


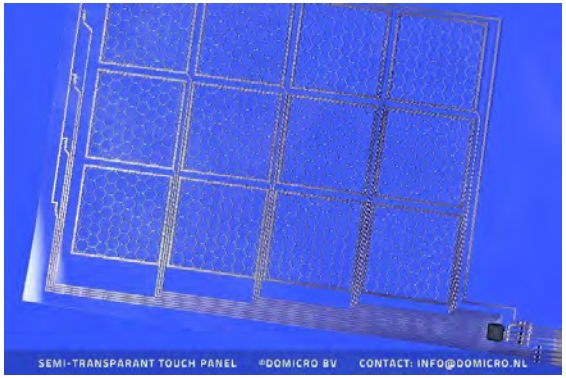


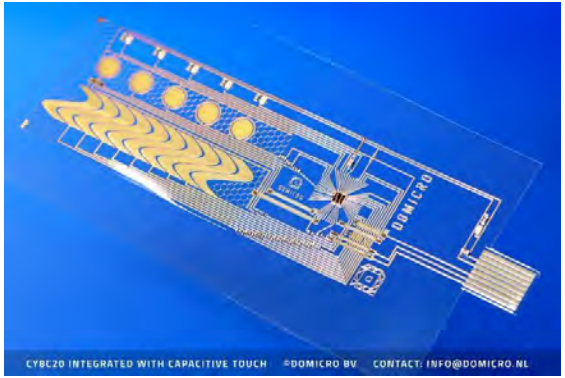


APPLICATIONS

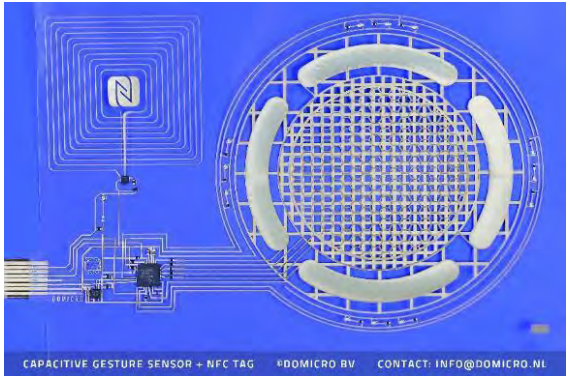






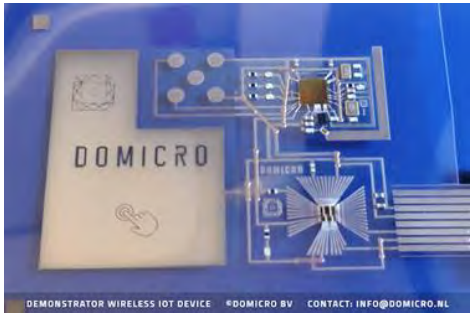




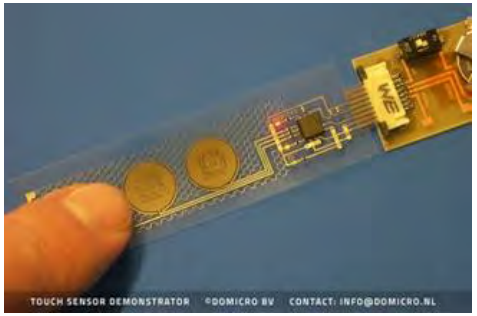


DOMICRO REFERENCES

Wireless IoT *(white paper)*

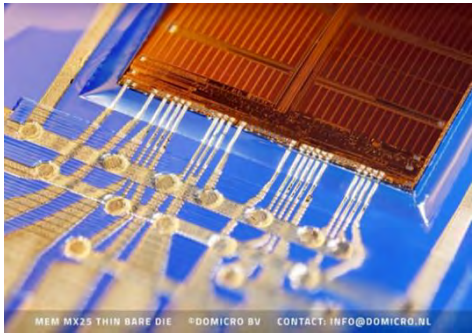


Touch sensor *(white paper)*

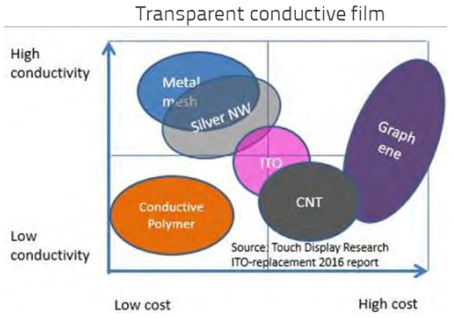


Click picture for hyperlink

Printed wirebonds *(video)*



EHD printing *(video)*



STRATEGIC BUSINESS RELATIONS

Innovation Funding



METROPOOL REGIO EINDHOVEN

Provincie Noord-Brabant

OPZuid

Co-funded by the European Union



Europese Unie

Europees Fonds voor Regionale Ontwikkeling

FlexMicro



EFROoost

Programme East Netherlands 2021-2027

European Regional Development Fund

Co-funded by the European Union

Value-added reseller Europe

CHEMCUBED

Jettable Solutions.™

Strategic Business Partners

PROMICRO ELECTRONICS DESIGN

High Tech NL

Brainport REGION Eindhoven

Flexible Hybrid Electronics & Micro Assembly Technologies

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